

EQUIPMENT DIVISION

Inseto's Equipment Division provides fabrication, assembly, test & inspection equipment for the research and production of semiconductor, microelectronic and related advanced electronic devices etc., as well as products for high technology & industrial manufacturing.

We are a leading supplier of lithography equipment for exposure, coating and development, inspection systems for substrates and advanced packaging, semiconductor furnaces, wafer bonders, probing systems, dicing saws and diamond scribes, die bonders and sorters, ultrasonic wire bonding machines, plasma cleaners and etching systems, vacuum solder reflow ovens, material testers for wire pull and shear testing etc.



LITHOGRAPHY EQUIPMENT BY SUSS MICROTEC

- High-quality UV mask and bond aligners
- Temporary and permanent wafer bonders
- Equipment for wafer clean, spin or spray coat & develop
- Stand-alone or integrated nanoimprint solutions
- R&D through fully automated cluster systems



WAFER PROBING SYSTEMS BY SEMIPROBE

- Affordable manual semi through automatic equipment
- Individual die, partial or full wafers from 50-450mm
- DC, HF ambient and thermal configurations
- Application specific: vacuum, HV-HC, MEMS, electro-optical etc.
- Modular and upgradable



BOND AND MICRO-MATERIALS TEST EQUIPMENT

- Multifunction bond testers for wire pull, die & bond shear, etc.
- Micro materials & advanced bond testing, including flex-bend, push-pull, crush, fatigue, creep, tweezer pull etc.
- Manual to fully automated test systems
- Test devices from -50 to 400°C

INSETO EQUIPMENT DIVISION



OPTICAL INSPECTION SYSTEMS BY NANOTRONICS

- Customised solutions for multiple processes from un-patterned and patterned wafers, through inspection of packaged devices
- Combining optical microscopy, computational super resolution, artificial intelligence and robotics
- Manual load through high-speed fully automated systems



THERMAL PROCESSING EQUIPMENT BY ATV

- Multi-purpose semiconductor quartz tube furnaces for research or production
- Table-top to in-line vacuum solder reflow & brazing systems
- Sintering press for LTCC and other applications
- Getter seal and high-vacuum activation system
- Precision hotplates



DICING EQUIPMENT & CONSUMABLES BY ADT

- Manual and semiautomatic wafer mounters
- Manual, semi & fully automatic dicing saws for silicon and hard materials
- Precision diamond scribes
- Peripheral equipment for washing, curing, filtration, cooling etc.
- Dicing blades & accessories



MANUAL DIE ATTACH & DIE SORT EQUIPMENT BY TRESKY AG

- Precision, flexible range of manual die bond, die sort and assembly systems
- Ergonomic controls with versatile modular designs
- High accuracy flip chip alignment capabilities
- Low-high force bonding option
- Large range of options for multiple die attach processes



AUTOMATIC DIE ATTACH & DIE SORT EQUIPMENT BY AMADYNE

- Stand-alone or in-line systems
- Processes include: dispensing, epoxy and eutectic bonding, die sorting, flip chip, bar stacking, inspection and test integration etc.
- Fully automatic models ideal for low through complex micro-systems assembly processes



SINTER EQUIPMENT & SAM INSPECTION SYSTEMS BY AMX

- Range of manual through in-line systems for die, component and lead-frame attach using silver, copper and other sinter pastes
- Micro-Punch" technology for uniform sinter pressure independent of die thickness
- In-line SAM inspection systems
- Sinter application laboratory to test material and processes



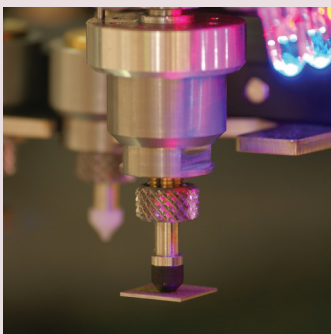
MANUAL WIRE BONDBERS BY MPP

- Formerly K&S manual wire bonder equipment division
- Models for ball & bump bonding or wedge & ribbon bonding
- Convertible ball & wedge bonding models
- All with touch screen and digital controls



AUTOMATIC WIRE BONDBERS BY KULICKE & SOFFA

- Automatic wedge bonders for microelectronic and battery bonding with wire or ribbon
- Manual load & in-line automatic ball bonders for microelectronic and semiconductor devices
- High speed automatic wafer bumpers for up to 300mm wafers
- Wire bonding capillaries



Established in 1987, and ISO-Certified since 2005, Inseto supplies equipment, materials and consumables to microelectronic manufacturers and research institutes in the UK, Ireland and Nordic Regions.

Customer support activities are at the centre of Inseto's "Total Customer Service" philosophy, where we aim to understand, communicate and fulfil the needs of our customers, better than any competitor. We are committed to meeting these requirements through the application of high standards of quality and customer care, both before and after sales, by continually investing in training & adopting a policy of continuous improvement in our Company and its people.